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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	MIPS-I
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	33MHz
Co-Processors/DSP	System Control; CP0
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	5.0V
Operating Temperature	0°C ~ 85°C (TC)
Security Features	-
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/idt79r3041-33pf

INTRODUCTION

The IDT RISController family is a series of high-performance 32-bit microprocessors featuring a high-level of integration, and targeted to high-performance but cost sensitive embedded processing applications. The RISController family is designed to bring the high-performance inherent in the MIPS RISC architecture into low-cost, simplified, power sensitive applications.

Thus, functional units have been integrated onto the CPU core in order to reduce the total system cost, rather than to increase the inherent performance of the integer engine. Nevertheless, the RISController family is able to offer 35MIPS of integer performance at 40MHz without requiring external SRAM or caches.

Further, the RISController family brings dramatic power reduction to these embedded applications, allowing the use of low-cost packaging. Thus, the RISController family allows customer applications to bring maximum performance at minimum cost.

The R3041 extends the range of price/performance achievable with the RISController family, by dramatically lowering the cost of using the MIPS architecture. The R3041 is designed to achieve minimal system and components cost, yet maintain the high-performance inherent in the MIPS architecture. The R3041 also maintains pin and software compatibility with the RISController and R3081.

The RISController family offers a variety of price/performance features in a pin-compatible, software compatible family. Table 1 provides an overview of the current members of the RISController family. Note that the R3051, R3052, and R3081 are also available in pin-compatible versions that include a full-function memory management unit, including 64-entry TLB. The R3051/2 and R3081 are described in separate manuals and data sheets.

Figure 1 shows a block level representation of the functional units within the R3041. The R3041 can be viewed as the embodiment of a discrete solution built around the R3000A. By integrating this functionality on a single chip, dramatic cost and power reductions are achieved.

An overview of these blocks is presented here, followed with detailed information on each block.

Device Name	Instruction Cache	Data Cache	Floating Point	Bus Options
R3051	4kB	2kB	Software Emulation	Mux'ed A/D
R3052	8kB	2kB	Software Emulation	Mux'ed A/D
R3071 R3081	16kB or 8kB	4kB or 8kB	On-chip Hardware	1/2 frequency bus option
R3041	2kB	512B	Software Emulation Programmable timing support	8-, 16-, and 32-bit port width support

2905 tbl 01

Table 1. Pin-Compatible RISController Family

CPU Core

The CPU core is a full 32-bit RISC integer execution engine, capable of sustaining close to a single cycle execution rate. The CPU core contains a five stage pipeline, and 32 orthogonal 32-bit registers. The RISController family implements the MIPS-I Instruction Set Architecture (ISA). In fact, the execution engine of the R3041 is the same as the execution engine of the R3000A. Thus, the R3041 is binary compatible with those CPU engines, as well as compatible with other members of the RISController family.

The execution engine of the RISController family uses a five-stage pipeline to achieve close to single cycle execution. A new instruction can be started in every clock cycle; the execution engine actually processes five instructions concurrently (in various pipeline stages). The five parts of the pipeline are the Instruction Fetch, Read register, ALU execution, Memory, and Write Back stages. Figure 2 shows the concurrency achieved by the RISController family pipeline.

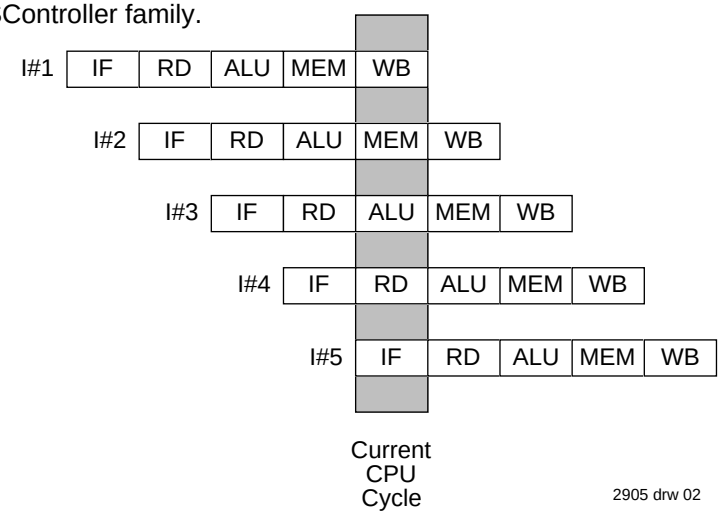


Figure 2. RISController Family 5-Stage Pipeline

R3041.

SYSTEM USAGE

The IDT RISController family is specifically designed to easily connect to low-cost memory systems. Typical low-cost memory systems use inexpensive EPROMs, DRAMs, and application specific peripherals.

Figure 4 shows some of the flexibility inherent in the R3041. In this example system, which is typical of a laser printer, a 32-bit PROM interface is used due to the size of the PDL interpreter. An embedded system can optionally use an 8-bit boot PROM instead. A 16-bit font/program cartridge interface is provided for add-in cards. A 16-bit DRAM interface is used for a low-cost page frame buffer. In this system example, a field or manufacturing upgrade to a 32-bit page frame buffer is supported by the boot software and DRAM controller. Embedded systems may optionally substitute SRAMs for the DRAMs. Finally various 8/16/32-bit I/O ports such as RS-232/422, SCSI, and LAN as well as the laser printer engine interface are supported. Such a system features a very low entry price, with a range of field upgrade options including the ability to upgrade to a more powerful member of the RISController family.

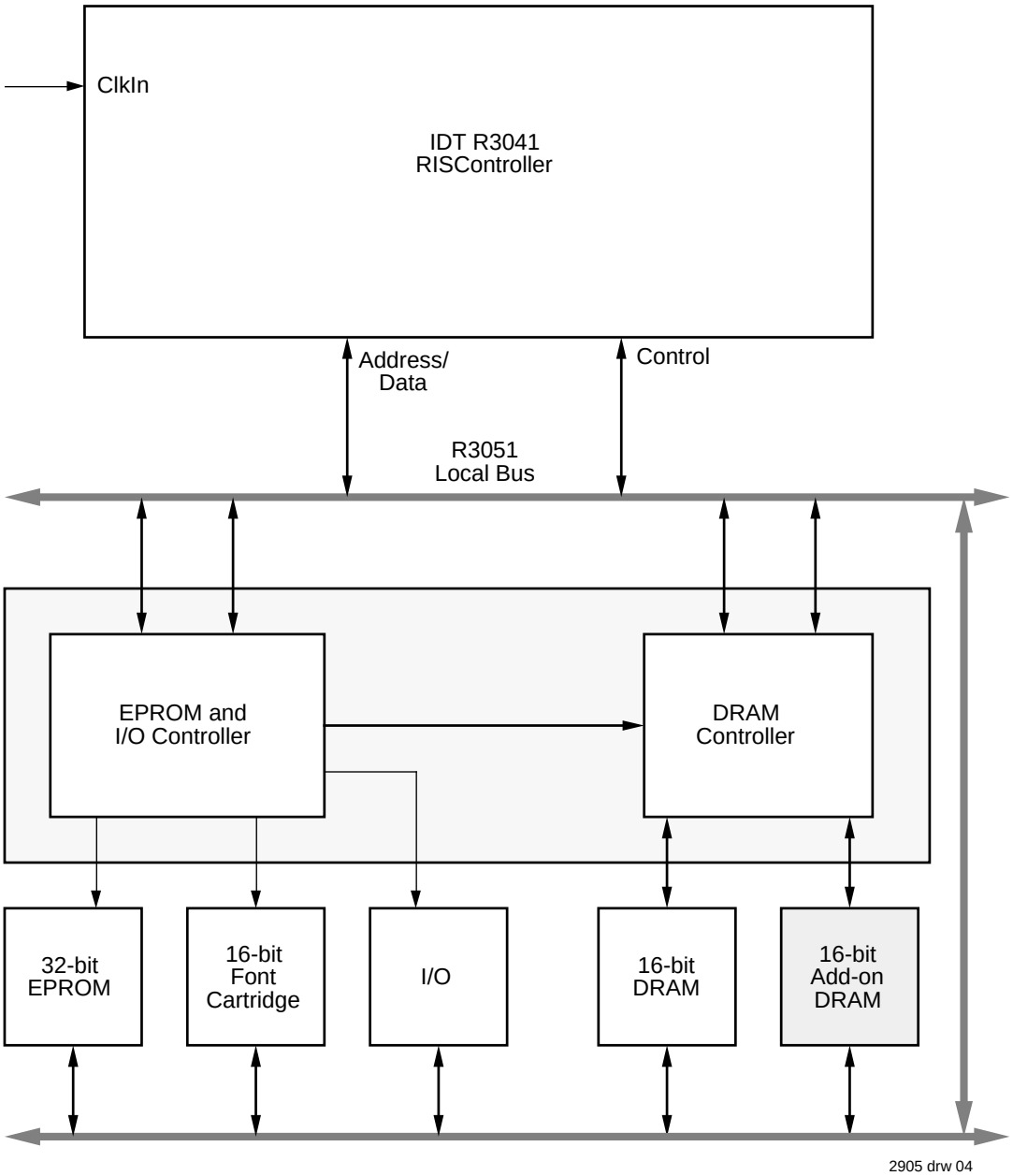


Figure 4. Typical R3041-Based Application

DEVELOPMENT SUPPORT

The IDT RISController family is supported by a rich set of development tools, ranging from system simulation tools through PROM monitor and debug support, applications software and utility libraries, logic analysis tools, and sub-system modules.

Figure 5 is an overview of the system development process typically used when developing R3041 applications. The RISController family is supported in all phases of project development. These tools allow timely, parallel development of hardware and software for RISController family based applications, and include tools such as:

- Optimizing compilers from MIPS Technology, the acknowledged leader in optimizing compiler technology.
- Cross development tools, available in a variety of development environments.
- The high-performance IDT floating point emulation library software.
- The IDT Evaluation Board, which includes RAM, EPROM, I/O, and the IDT PROM Monitor.
- IDT Laser Printer System boards, which directly drive a low-cost print engine, and runs Adobe PostScript™ Page Description Language
- Adobe PostScript Page Description Language running on the IDT RISController family.
- The IDT/sim™ PROM Monitor, which implements a full PROM monitor (diagnostics, remote debug support, peek/

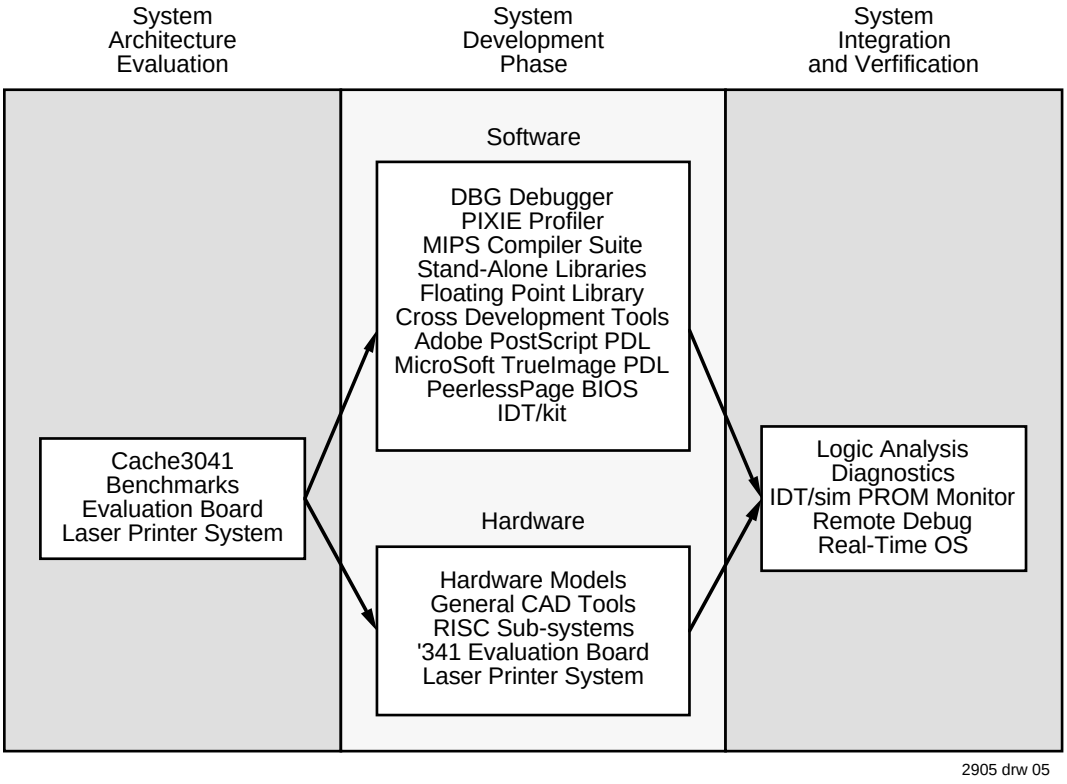
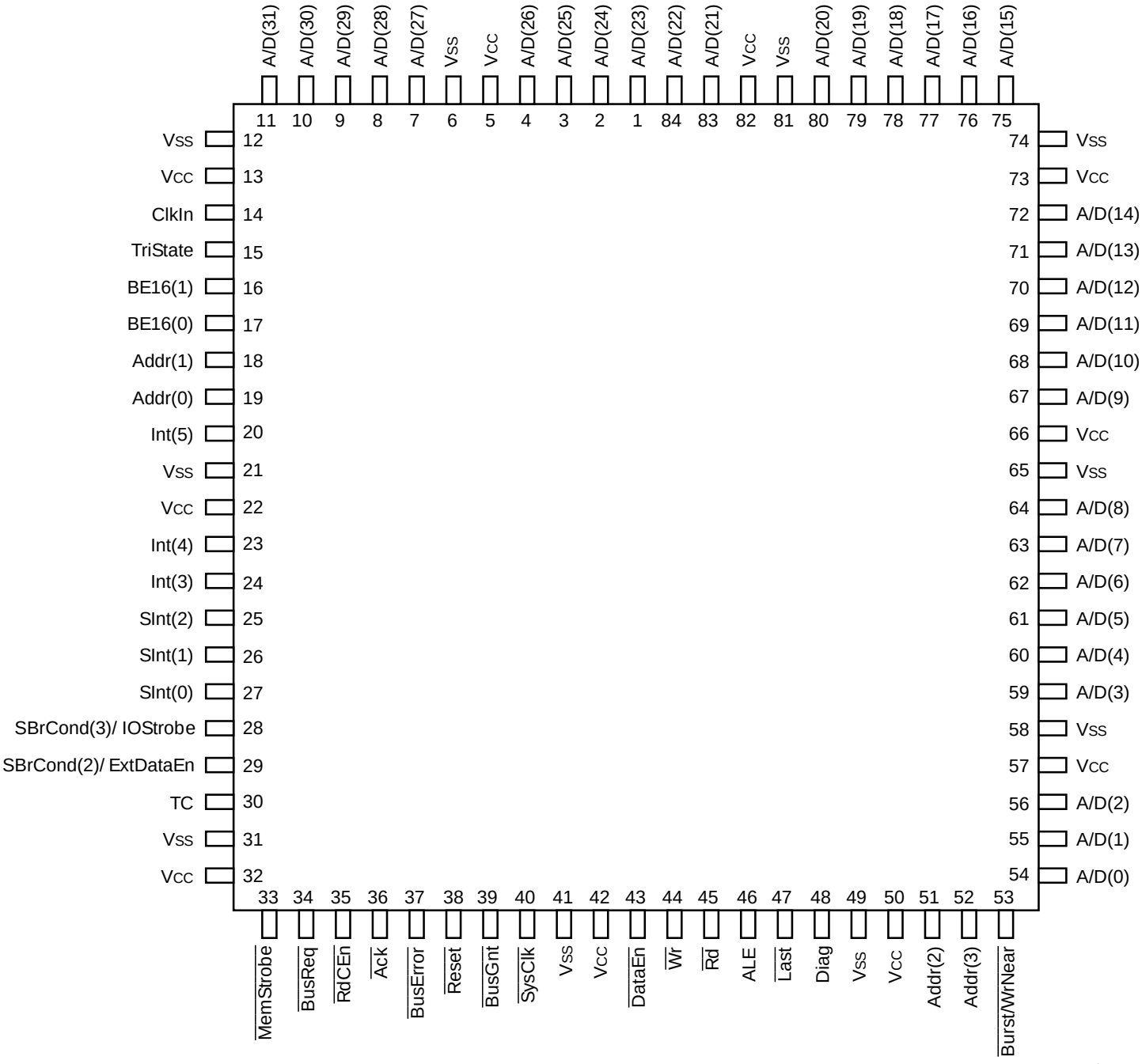


Figure 5. R3041 Development Environment

PIN CONFIGURATIONS

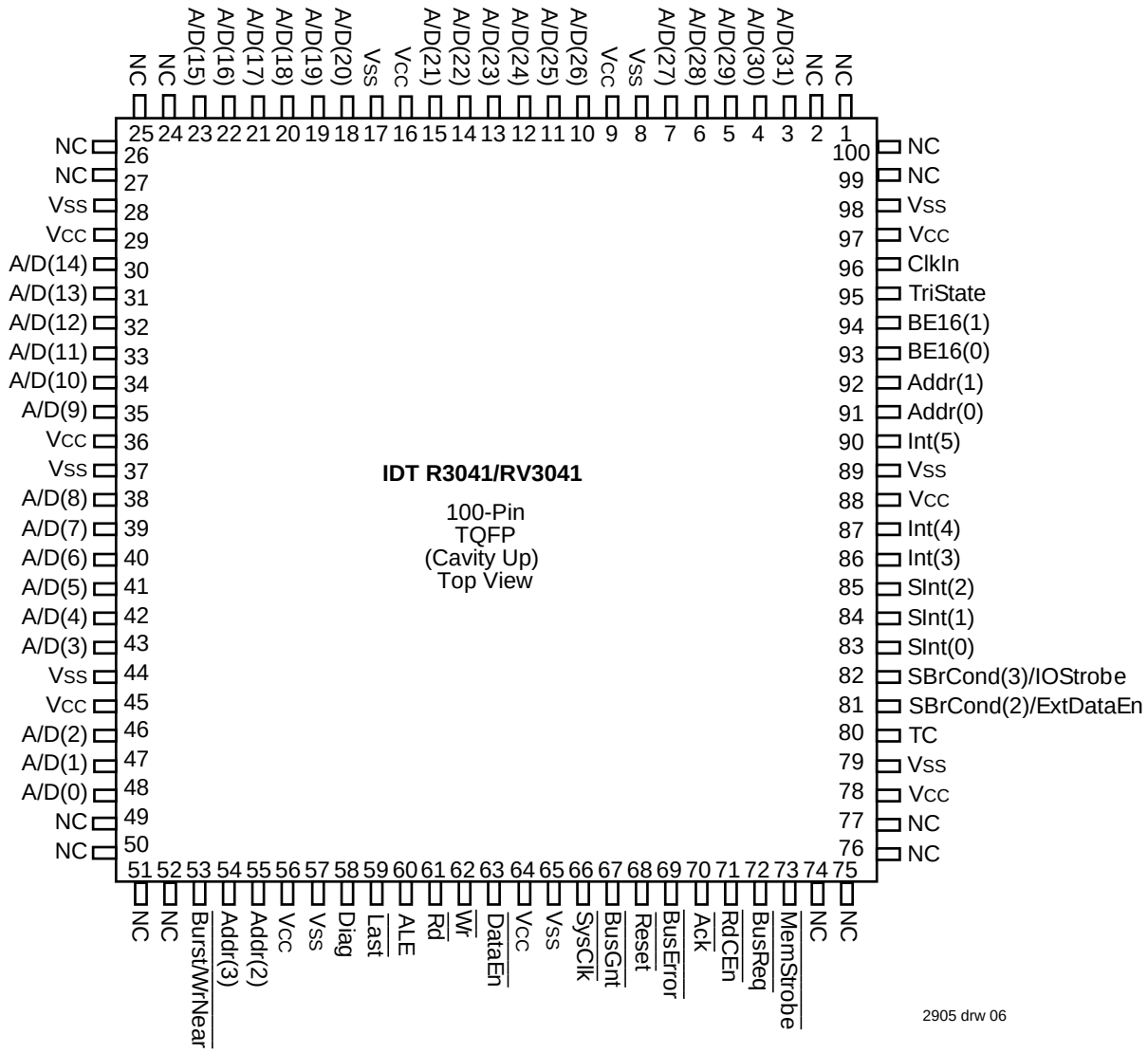


2905 drw 06

84-Pin PLCC/
Top View

(Cavity Down)

PIN CONFIGURATIONS



2905 drw 06

PIN DESCRIPTION

PIN NAME	I/O	DESCRIPTION
A/D(31:0)	I/O	**Address/Data:** A 32-bit time multiplexed bus which indicates the desired address for a bus transaction in one phase, and which is used to transmit data between the CPU and external memory resources during the rest of the transfer. Bus transactions on this bus are logically separated into two phases: during the first phase, information about the transfer is presented to the memory system to be captured using the ALE output. This information consists of: **Address(31:4)**: The high-order address for the transfer is presented on A/D(31:4). $\overline{BE(3:0)}$: These strobes indicate which bytes of the 32-bit bus will be involved in the transfer, and are presented on A/D(3:0). $\overline{BE(3)}$ indicates that A/D(31:24) will be used, and $\overline{BE(0)}$ corresponds to A/D(7:0). These strobes are only valid for accesses to 32-bit wide memory ports. Note that $\overline{BE(3:0)}$ can be held in-active during reads by setting the appropriate bit of CP0; thus when latched, these signals can be directly used as Write Enable strobes. During the second phase, these signals are the data bus for the transaction. **Data(31:0):** During write cycles, the bus contains the data to be stored and is driven from the internal write buffer. On read cycles, the bus receives the data from the external resource, in either a single data transaction or in a burst of four words, and places it into the on-chip read buffer. The byte lanes used during the transfer are a function of the datum size, the memory port width, and the system byte-ordering.
Addr(3:0)	O I[1]	**Low Address (3:0)** A 4-bit bus which indicates which word/halfword/byte is currently expected by the processor. For 32-bit port widths, only Addr(3:2) is valid during the transfer; for 16-bit port widths, only Addr(3:1) are valid; for 8-bit port widths, all of Addr(3:0) are valid. These address lines always contain the address of the current datum to be transferred. In writes and single datum reads, the addresses initially output the specific target address, and will increment if the size of the datum is wider than the target memory port. For quad word reads, these outputs function as a counter starting at '0000', and incrementing according to the width of the memory port. During $\overline{Reset}$, the Addr(3:0) pins act as Reset Configuration Mode bit inputs for the $\overline{BootProm16}$, $\overline{BootProm8}$, ReservedHigh, and $\overline{ExtAddrHold}$ options. The R3041 Addr(1:0) output pins are designated as the unconnected Rsvd(1:0) pins in the R3051 and R3081.
Diag	O	**Diagnostic Pin.** This output indicates whether the current bus read transaction is due to an on-chip cache miss and whether the read is an instruction or data. It is time multiplexed as described below: **Cached/**$\overline{Uncached}$**:** During the phase in which the A/D bus presents address information, this pin is an active high output which indicates whether or not the current read is a result of a cache miss. The value of this pin at this time other than in read cycles is undefined. **I/**$\overline{D}$: A high at this time indicates an instruction reference, and a low indicates a data reference. The value of this pin at this time other than in read cycles is undefined. The R3041 Diag output pin is designated as the Diag(1) output pin in the R3051 and R3081.
ALE	O	**Address Latch Enable:** Used to indicate that the A/D bus contains valid address information for the bus transaction. This signal is used by external logic to capture the address for the transfer, typically by using transparent latches.
$\overline{DataEn}$	O	**Data Enable:** This signal indicates that the A/D bus is no longer being driven by the processor during read cycles, and thus the external memory system may enable the drivers of the memory system onto this bus without having a bus conflict occur. During write cycles, or when no bus transaction is occurring, this signal is negated, thus disabling the external memory drivers.

NOTE:
1. Reset Configuration Mode bit input when $\overline{Reset}$ is asserted, normal signal function when $\overline{Reset}$ is de-asserted.

2905 tbl 03

ABSOLUTE MAXIMUM RATINGS(1, 3) R3041

Symbol	Rating	Commercial	Unit
V_{TERM}	Terminal Voltage with Respect to GND	–0.5 to +7.0	V
T_C	Operating Case Temperature	0 to +85	°C
T_{BIAS}	Temperature Under Bias	–55 to +125	°C
T_{STG}	Storage Temperature	–55 to +125	°C
V_{IN}	Input Voltage	–0.5 to +7.0	V

2905 tbl 06

NOTES:
1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. V_{IN} minimum = –3.0V for pulse width less than 15ns. V_{IN} should not exceed V_{CC} +0.5 Volts.
3. Not more than one output should be shorted at a time. Duration of the short should not exceed 30 seconds.

AC TEST CONDITIONS R3041

Symbol	Parameter	Min.	Max.	Unit
V_{IH}	Input HIGH Voltage	3.0	—	V
V_{IL}	Input LOW Voltage	—	0	V
V_{IHS}	Input HIGH Voltage	3.5	—	V
V_{ILS}	Input LOW Voltage	—	0	V

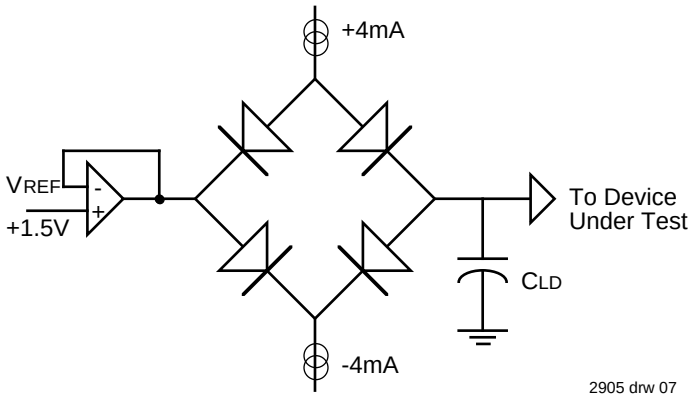
2905 tbl 08

RECOMMENDED OPERATING TEMPERATURE AND SUPPLY VOLTAGE

Grade	Temperature	GND	Vcc
Commercial	0°C to +85°C (Case)	0V	5.0 ±5%

2905 tbl 07

OUTPUT LOADING FOR AC TESTING



2905 drw 07

Signal	Cld
All Signals	25 pF

2905 tbl 09

DC ELECTRICAL CHARACTERISTICS R3041 — (T_C = 0°C to +85°C, V_{CC} = +5.0V ±5%)

Symbol	Parameter	Test Conditions	16.67MHz		20MHz		25MHz		33MHz		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
V_{OH}	Output HIGH Voltage	V_{CC} = Min., I_{OH} = –4mA	3.5	—	3.5	—	3.5	—	3.5	—	V
V_{OL}	Output LOW Voltage	V_{CC} = Min., I_{OL} = 4mA	—	0.4	—	0.4	—	0.4	—	0.4	V
V_{IH}	Input HIGH Voltage(3)	—	2.0	—	2.0	—	2.0	—	2.0	—	V
V_{IL}	Input LOW Voltage(1)	—	—	0.8	—	0.8	—	0.8	—	0.8	V
V_{IHS}	Input HIGH Voltage(2,3)	—	3.0	—	3.0	—	3.0	—	3.0	—	V
V_{ILS}	Input LOW Voltage(1,2)	—	—	0.4	—	0.4	—	0.4	—	0.4	V
C_{IN}	Input Capacitance(4)	—	—	10	—	10	—	10	—	10	pF
C_{OUT}	Output Capacitance(4)	—	—	10	—	10	—	10	—	10	pF
I_{CC}	Operating Current	V_{CC} = 5V, T_C = 25°C	—	225	—	250	—	300	—	370	mA
I_{IH}	Input HIGH Leakage	V_{IH} = VCC	—	100	—	100	—	100	—	100	µA
I_{IL}	Input LOW Leakage	V_{IL} = GND	–100	—	–100	—	–100	—	–100	—	µA
I_{OZ}	Output Tri-state Leakage	V_{OH} = 2.4V, V_{OL} = 0.5V	–100	100	–100	100	–100	100	–100	100	µA

2905 tbl 10

NOTES:
1. V_{IL} Min. = –3.0V for pulse width less than 15ns. V_{IL} should not fall below –0.5 volts for larger periods.
2. V_{IHS} and V_{ILS} apply to ClkIn and $\overline{\text{Reset}}$.
3. V_{IH} should not be held above V_{CC} + 0.5 volts.
4. Guaranteed by design.

AC ELECTRICAL CHARACTERISTICS R3041 (1, 2, 3)— (T_C = 0°C to +85°C, V_{CC} = +5.0V ±5%)

Symbol	Signals	Description	16.67MHz		20MHz		25MHz		33MHz		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t1	$\overline{BusReq}$, $\overline{Ack}$, $\overline{BusError}$, $\overline{RdCEn}$	Set-up to $\overline{SysClk}$ rising	11	—	8	—	5.5	—	5.5	—	ns
t1a	A/D	Set-up to $\overline{SysClk}$ falling	12	—	9	—	7	—	7	—	ns
t2	$\overline{BusReq}$, $\overline{Ack}$, $\overline{BusError}$, $\overline{RdCEn}$	Hold from $\overline{SysClk}$ rising	4	—	3	—	2.5	—	2.5		ns
t2a	A/D	Hold from $\overline{SysClk}$ falling	2	—	2	—	1	—	1	—	ns
t3	A/D, Addr, Diag, ALE, $\overline{Wr}$ $\overline{Burst/WrNear}$, $\overline{Rd}$, $\overline{DataEn}$	Tri-state from SysClk rising (after driven condition)	—	13	—	10	—	10	—	10	ns
t4	A/D, Addr, Diag, ALE, $\overline{Wr}$ $\overline{Burst/WrNear}$, $\overline{Rd}$, $\overline{DataEn}$	Driven from $\overline{SysClk}$ falling (after tri-state condition)	—	13	—	10	—	10	—	10	ns
t5	$\overline{BusGnt}$	Asserted from $\overline{SysClk}$ rising	—	10	—	8	—	7	—	7	ns
t6	$\overline{BusGnt}$	Negated from $\overline{SysClk}$ falling	—	10	—	8	—	7	—	7	ns
t7	$\overline{Wr}$, $\overline{Rd}$, $\overline{Burst/WrNear}$, $\overline{TC}$	Valid from $\overline{SysClk}$ rising	—	8	—	6	—	5	—	5	ns
t7a	A/D	Valid from $\overline{SysClk}$ rising	—	12	—	9	—	8	—	8	ns
t7b	$\overline{Last}$	Valid from $\overline{SysClk}$ rising	—	12	—	9	—	8	—	8	ns
t8	ALE	Asserted from $\overline{SysClk}$ rising	—	5	—	4	—	4	—	4	ns
t9	ALE	Negated from $\overline{SysClk}$ falling	—	5	—	4	—	4	—	4	ns
t10	A/D	Hold from ALE negated	2	—	2	—	2	—	1.5		ns
t11	$\overline{DataEn}$	Asserted from $\overline{SysClk}$	—	19	—	15	—	15	—	15	ns
t12	$\overline{DataEn}$	Asserted from A/D tri-state(4)	0	—	0	—	0	—	0	—	ns
t14	A/D	Driven from $\overline{SysClk}$ rising(4)	0	—	0	—	0	—	0	—	ns
t15	$\overline{Wr}$, $\overline{Rd}$, $\overline{DataEn}$, $\overline{Burst/WrNear}$, $\overline{Last}$, $\overline{TC}$	Negated from $\overline{SysClk}$ falling	—	9	—	7	—	6	—	6	ns
t16	Addr(3:0), $\overline{BE\ 16(1:0)}$	Valid from $\overline{SysClk}$	—	11	—	8	—	7	—	7	ns
t17	Diag	Valid from $\overline{SysClk}$	—	15	—	12	—	11	—	11	ns
t18	A/D	Tri-state from $\overline{SysClk}$	—	13	—	10	—	10	—	10	ns
t19	A/D	$\overline{SysClk}$ to data out	—	16	—	13	—	12	—	12	ns
t20	ClkIn	Pulse Width High	12	—	10	—	8	—	6.5	—	ns
t21	ClkIn	Pulse Width Low	12	—	10	—	8	—	6.5	—	ns
t22	ClkIn	Clock Period	30	250	25	250	20	250	15	250	ns
t23	$\overline{Reset}$	Pulse Width from Vcc valid	200	—	200	—	200	—	200	—	µs
t24	$\overline{Reset}$	Minimum Pulse Width	32	—	32	—	32	—	32	—	sys
t25	$\overline{Reset}$	Set-up to $\overline{SysClk}$ falling	8	—	6	—	5	—	5	—	ns
t26	$\overline{Int}$	Mode set-up to $\overline{Reset}$ rising	8	—	6	—	5	—	5	—	ns
t27	$\overline{Int}$	Mode hold from $\overline{Reset}$ rising	2.5	—	2.5	—	2.5	—	2.5	—	ns
t28	$\overline{SInt}$, SBrCond	Set-up to $\overline{SysClk}$ falling	8	—	6	—	5	—	5	—	ns
t29	$\overline{SInt}$, SBrCond	Hold from $\overline{SysClk}$ falling	4	—	3	—	3	—	3	—	ns
t30	$\overline{Int}$, BrCond	Set-up to $\overline{SysClk}$ falling	8	—	6	—	5	—	5	—	ns
t31	$\overline{Int}$, BrCond	Hold from $\overline{SysClk}$ falling	4	—	3	—	3	—	3	—	ns
tsys	$\overline{SysClk}$	Pulse Width	2*t22	2*t22	2*t22	2*t22	2*t22	2*t22	2*t22	2*t22	ns
t32	$\overline{SysClk}$	Clock High Time	t22 - 2	t22 + 2	t22 - 2	t22 + 2	t22 - 2	t22 + 2	t22 - 2	t22 + 2	ns
t33	$\overline{SysClk}$	Clock Low Time	t22 - 2	t22 + 2	t22 - 2	t22 + 2	t22 - 2	t22 + 2	t22 - 2	t22 + 2	ns

2905 tbl 11

AC ELECTRICAL CHARACTERISTICS R3041 (CONT.)

Symbol	Signals	Description	16.67MHz		20MHz		25MHz		33MHz		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t45	ExtDataEn	Tri-state from SysClk rising (after driven condition)	—	13	—	10	—	10	—	10	ns
t46	$\overline{\text{ExtDataEn}}$	Driven from $\overline{\text{SysClk}}$ falling (after driven condition)	—	13	—	10	—	10	—	10	ns
t47	$\overline{\text{IOStrobe}}$	Valid from $\overline{\text{SysClk}}$ falling	—	10	—	8	—	7	—	7	ns
t48	$\overline{\text{ExtDataEn}}$, $\overline{\text{DataEn}}$	Asserted from $\overline{\text{SysClk}}$ rising	—	15	—	12	—	9	—	9	ns
t49	$\overline{\text{ExtDataEn}}$	Negated from $\overline{\text{SysClk}}$ rising	—	9	—	7	—	6	—	6	ns
t50	$\overline{\text{MemStrobe}}$	Asserted from $\overline{\text{SysClk}}$ rising	—	19	—	15	—	15	—	15	ns
t51	$\overline{\text{MemStrobe}}$	Negated from $\overline{\text{SysClk}}$ falling	—	19	—	15	—	15	—	15	ns
t52	$\overline{\text{MemStrobe}}$	Asserted from Addr(3:0) valid(4)	0	—	0	—	0	—	0	—	ns
tderate	All outputs	Timing deration for loading over 25pF(4, 5)	—	0.5	—	0.5	—	0.5	—	0.5	ns/ 25pF

NOTES: 2905 tbl 12

1. All timings referenced to 1.5 Volts, with a rise and fall time of less than 2.5ns.
2. All outputs tested with 25pF loading.
3. The AC values listed here reference timing diagrams contained in the R3041 Hardware User's Manual.
4. Guaranteed by design.
5. This parameter is used to derate the AC timings according to the loading of the system. This parameter provides a deration for loads over the specified test condition; that is, the deration factor is applied for each 25pF over the specified test load condition.
6. Timings t34 - t44 are reserved for other RISController family members.

ABSOLUTE MAXIMUM RATINGS(1, 3) RV3041

Symbol	Rating	Commercial	Unit
V_{TERM}	Terminal Voltage with Respect to GND	–0.5 to +7.0	V
T_C	Operating Case Temperature	0 to +85	°C
T_{BIAS}	Temperature Under Bias	–55 to +125	°C
T_{STG}	Storage Temperature	–55 to +125	°C
V_{IN}	Input Voltage	–0.5 to +7.0	V

NOTES: 2905 tbl 06

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. V_{IN} minimum = –3.0V for pulse width less than 15ns. V_{IN} should not exceed V_{CC} +0.5 Volts.
3. Not more than one output should be shorted at a time. Duration of the short should not exceed 30 seconds.

AC TEST CONDITIONS RV3041

Symbol	Parameter	Min.	Max.	Unit
V_{IH}	Input HIGH Voltage	3.0	—	V
V_{IL}	Input LOW Voltage	—	0	V
V_{IHS}	Input HIGH Voltage	3.0	—	V
V_{ILS}	Input LOW Voltage	—	0	V

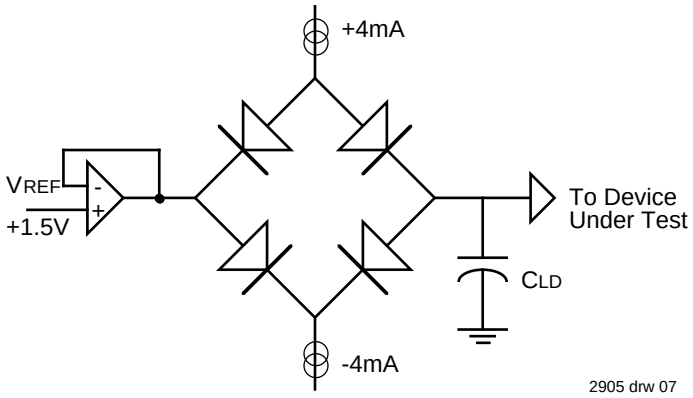
2905 tbl 08

RECOMMENDED OPERATING TEMPERATURE AND SUPPLY VOLTAGE

Grade	Temperature	GND	Vcc
Commercial RV3041	0°C to +85°C (Case)	0V	3.3 ±5%

2905 tbl 07

OUTPUT LOADING FOR AC TESTING



2905 drw 07

Signal	Cld
All Signals	25 pF

2905 tbl 09

AC ELECTRICAL CHARACTERISTICS RV3041 (CONT.)

Symbol	Signals	Description	16.67 MHz		20 MHz		25MHz		33MHz		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t18	A/D	Tri-state from $\overline{\text{SysClk}}$	—	13	—	10	—	10	—	10	ns
t19	A/D	$\overline{\text{SysClk}}$ to data out	—	16	—	13	—	12	—	12	ns
t20	ClkIn	Pulse Width High	12	—	10	—	8	—	6.5	—	ns
t21	ClkIn	Pulse Width Low	12	—	10	—	8	—	6.5	—	ns
t22	ClkIn	Clock Period	30	250	25	250	20	250	15	250	ns
t23	$\overline{\text{Reset}}$	Pulse Width from Vcc valid	200	—	200	—	200	—	200	—	µs
t24	$\overline{\text{Reset}}$	Minimum Pulse Width	32	—	32	—	32	—	32	—	sys
t25	$\overline{\text{Reset}}$	Set-up to $\overline{\text{SysClk}}$ falling	8	—	6	—	5	—	5	—	ns
t26	$\overline{\text{Int}}$	Mode set-up to $\overline{\text{Reset}}$ rising	8	—	6	—	5	—	5	—	ns
t27	$\overline{\text{Int}}$	Mode hold from $\overline{\text{Reset}}$ rising	2.5	—	2.5	—	2.5	—	2.5	—	ns
t28	$\overline{\text{SInt}}$, SBrCond	Set-up to $\overline{\text{SysClk}}$ falling	8	—	6	—	5	—	5	—	ns
t29	$\overline{\text{SInt}}$, SBrCond	Hold from $\overline{\text{SysClk}}$ falling	4	—	3	—	3	—	3	—	ns
t30	$\overline{\text{Int}}$, BrCond	Set-up to $\overline{\text{SysClk}}$ falling	8	—	6	—	5	—	5	—	ns
t31	$\overline{\text{Int}}$, BrCond	Hold from $\overline{\text{SysClk}}$ falling	4	—	3	—	3	—	3	—	ns
tsys	$\overline{\text{SysClk}}$	Pulse Width	2*t22	2*t22	2*t22	2*t22	2*t22	2*t22	2*t22	2*t22	ns
t32	$\overline{\text{SysClk}}$	Clock High Time	t22 - 2	t22 + 2	t22 - 2	t22 + 2	t22 - 2	t22 + 2	t22 - 2	t22 + 2	ns
t33	$\overline{\text{SysClk}}$	Clock Low Time	t22 - 2	t22 + 2	t22 - 2	t22 + 2	t22 - 2	t22 + 2	t22 - 2	t22 + 2	ns
t45	$\overline{\text{ExtDataEn}}$	Tri-state from $\overline{\text{SysClk}}$ rising (after driven condition)	—	13	—	10	—	10	—	10	ns
t46	$\overline{\text{ExtDataEn}}$	Driven from $\overline{\text{SysClk}}$ falling (after driven condition)	—	13	—	10	—	10	—	10	ns
t47	$\overline{\text{IOStrobe}}$	Valid from $\overline{\text{SysClk}}$ falling	—	10	—	8	—	7	—	7	ns
t48	$\overline{\text{ExtDataEn}}$,	Asserted from $\overline{\text{SysClk}}$ rising	—	15	—	12	—	9	—	9	ns
t49	$\overline{\text{ExtDataEn}}$ $\overline{\text{DataEn}}$	Negated from $\overline{\text{SysClk}}$ rising	—	9	—	7	—	6	—	6	ns
t50	$\overline{\text{MemStrobe}}$	Asserted from $\overline{\text{SysClk}}$ rising	—	19	—	15	—	15	—	15	ns
t51	$\overline{\text{MemStrobe}}$	Negated from $\overline{\text{SysClk}}$ falling	—	19	—	15	—	15	—	15	ns
t52	$\overline{\text{MemStrobe}}$	Asserted from Addr(3:0) valid(4)	0	—	0	—	0	—	0	—	ns
tderate	All outputs	Timing deration for loading over 25pF(4, 5)	—	0.5	—	0.5	—	0.5	—	0.5	ns/ 25pF

NOTES:

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1. All timings referenced to 1.5 Volts, with a rise and fall time of less than 2.5ns.
2. All outputs tested with 25pF loading.
3. The AC values listed here reference timing diagrams contained in the R3041 Hardware User's Manual.
4. Guaranteed by design.
5. This parameter is used to derate the AC timings according to the loading of the system. This parameter provides a deration for loads over the specified test condition; that is, the deration factor is applied for each 25pF over the specified test load condition.
6. Timings t34 - t44 are reserved for other RISController family members.

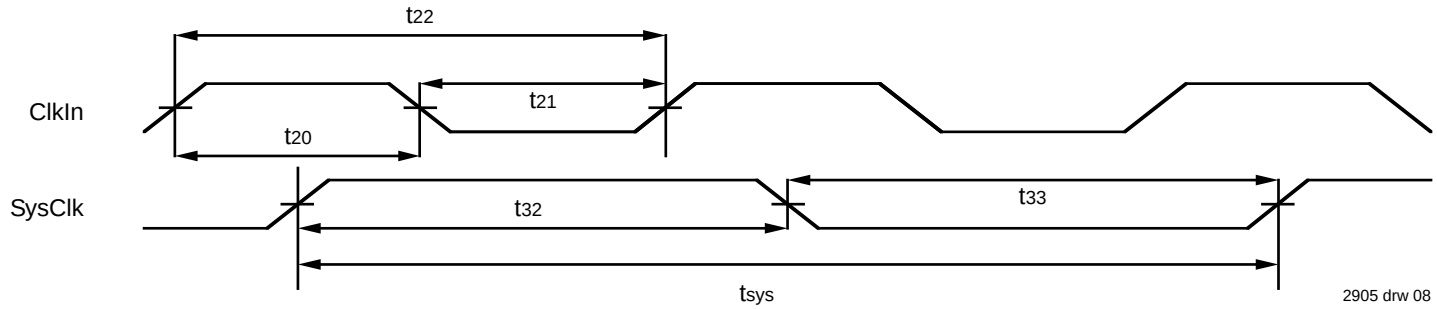


Figure 8. RISController Family Clocking

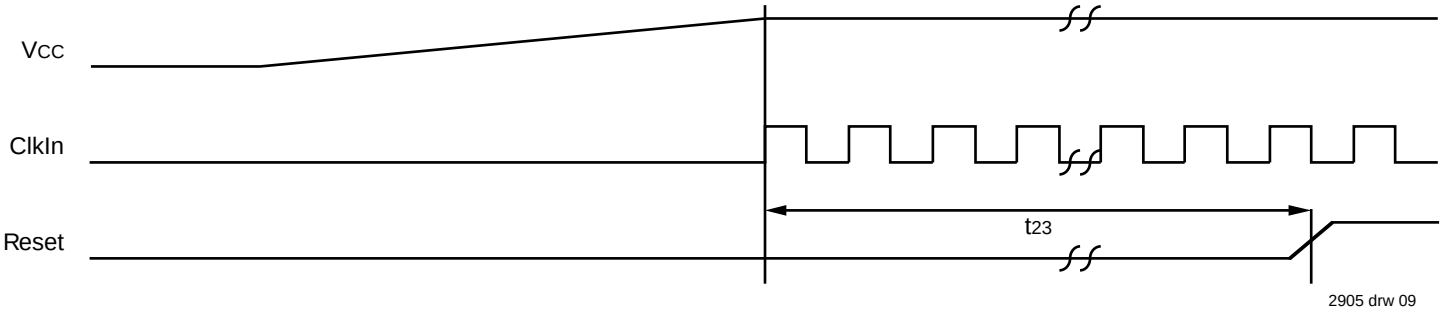


Figure 9. Power-On Reset Sequence

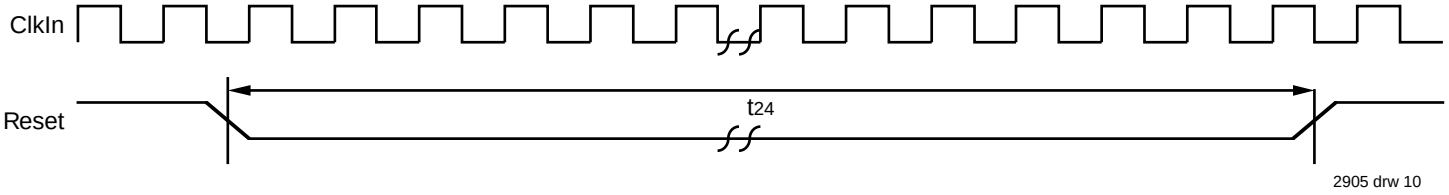


Figure 10(a). Warm Reset Sequence

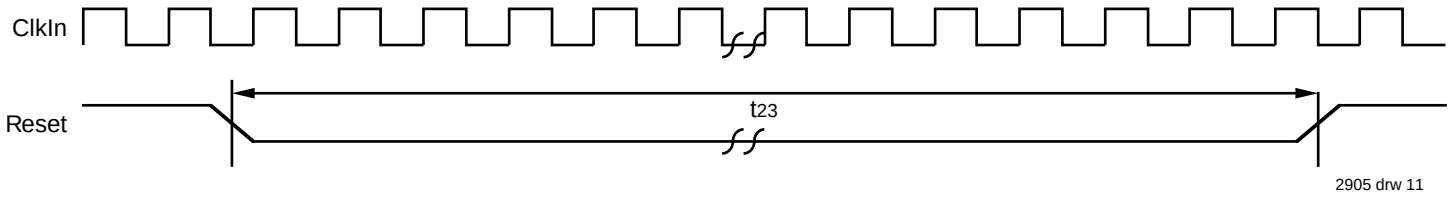


Figure 10(b). Warm Reset Sequence (Internal Pull-Ups Used)

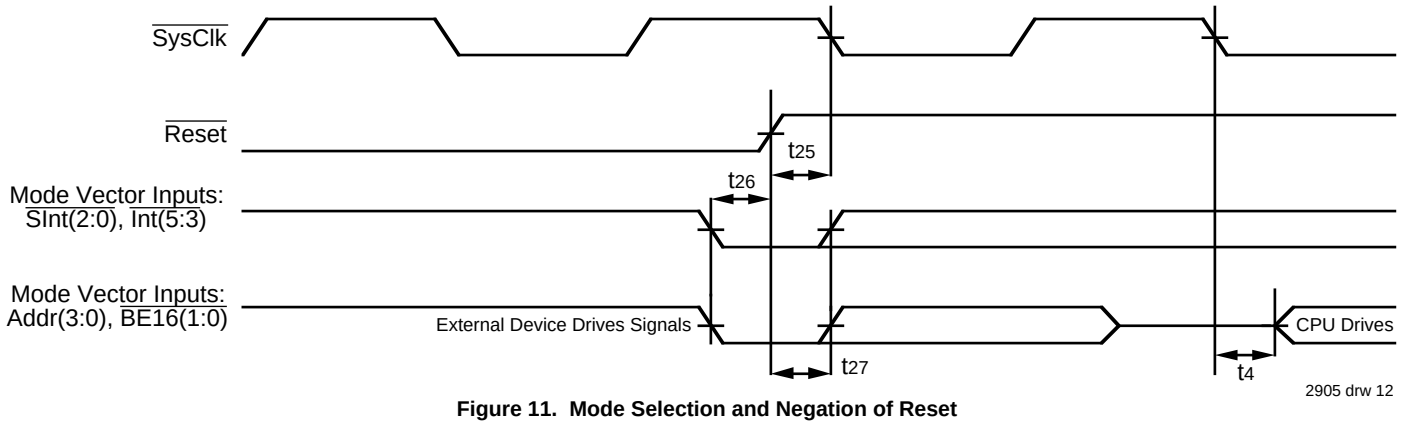


Figure 11. Mode Selection and Negation of Reset

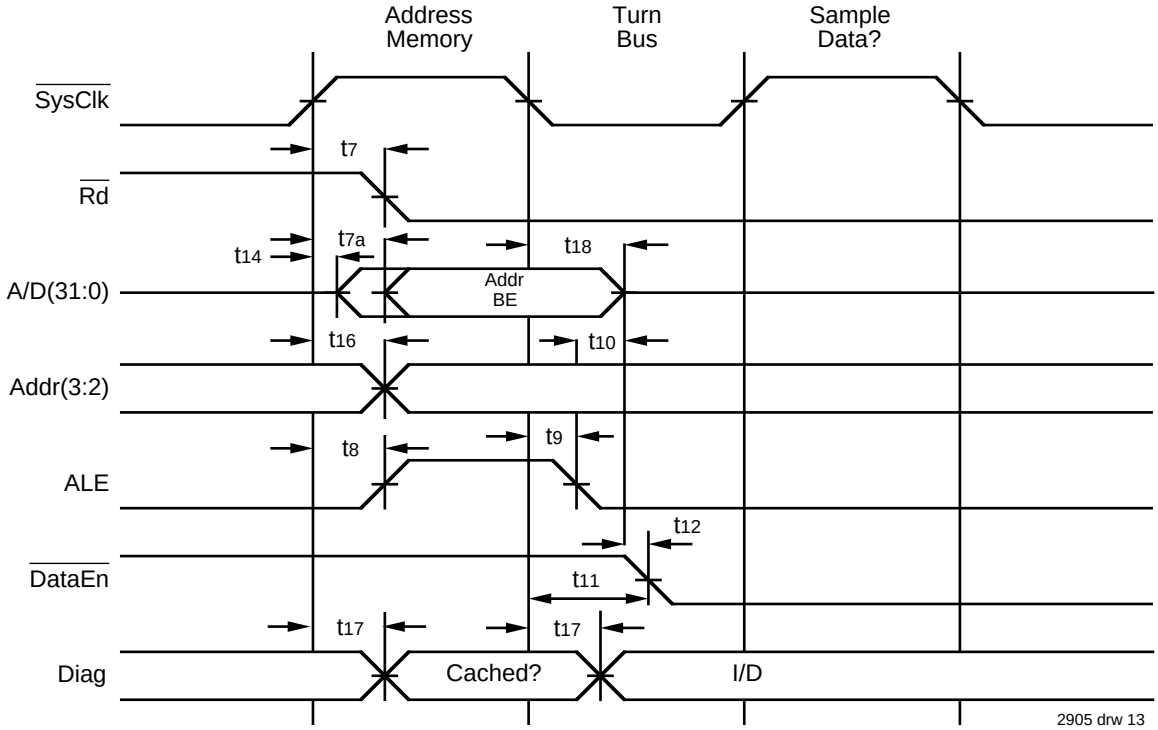


Figure 12(a). Start of Read Timing with Non-Extended Address Hold Option

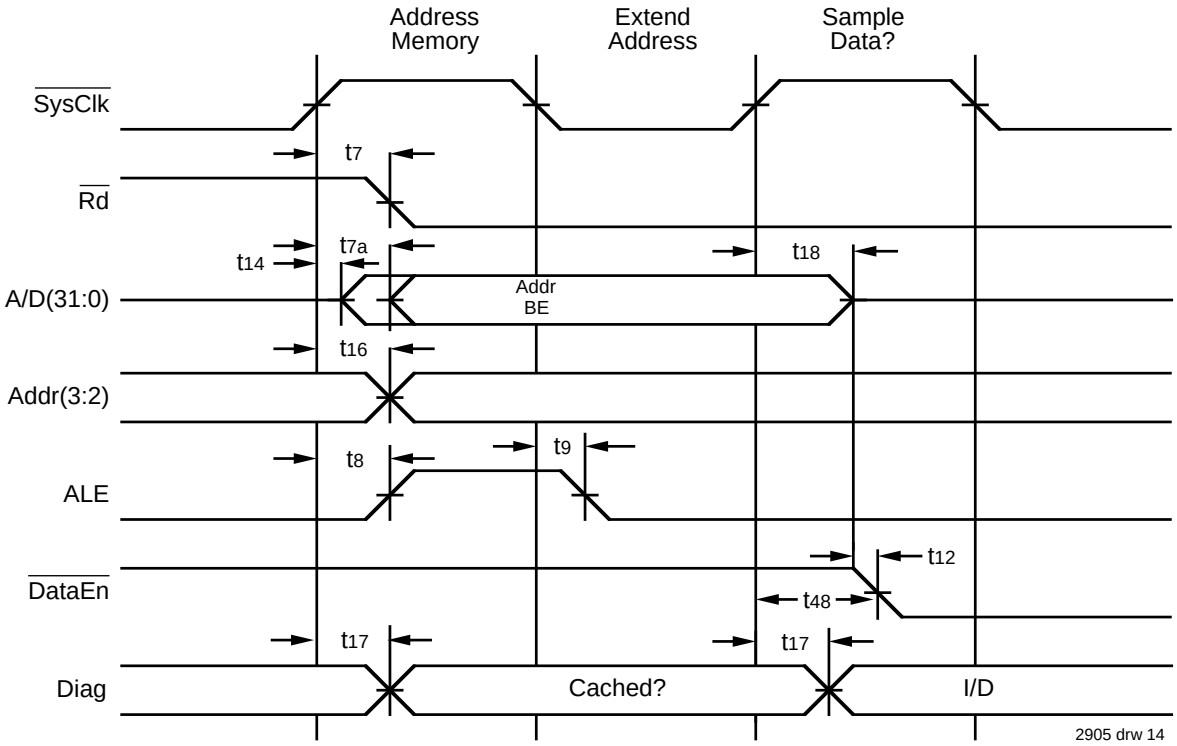


Figure 12(b). Start of Read Timing with Extended Address Hold Option

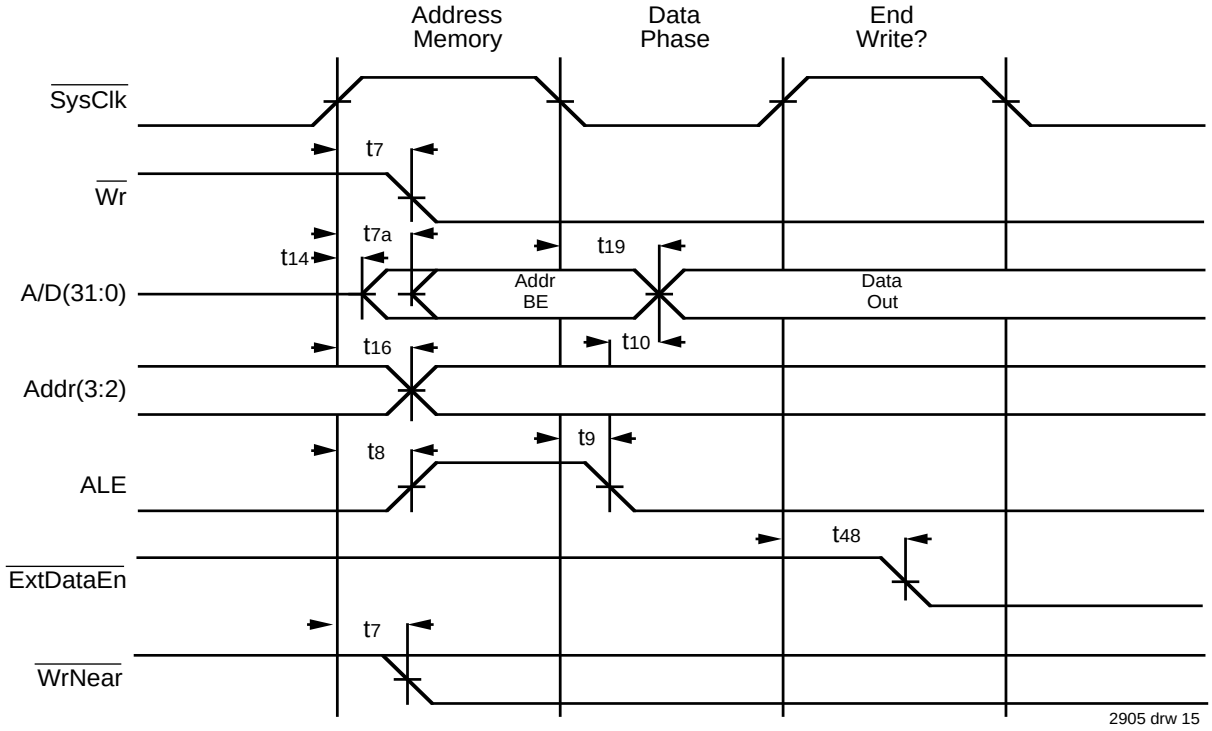


Figure 12(c). Start of Write Timing with Non-Extended Address Hold Option

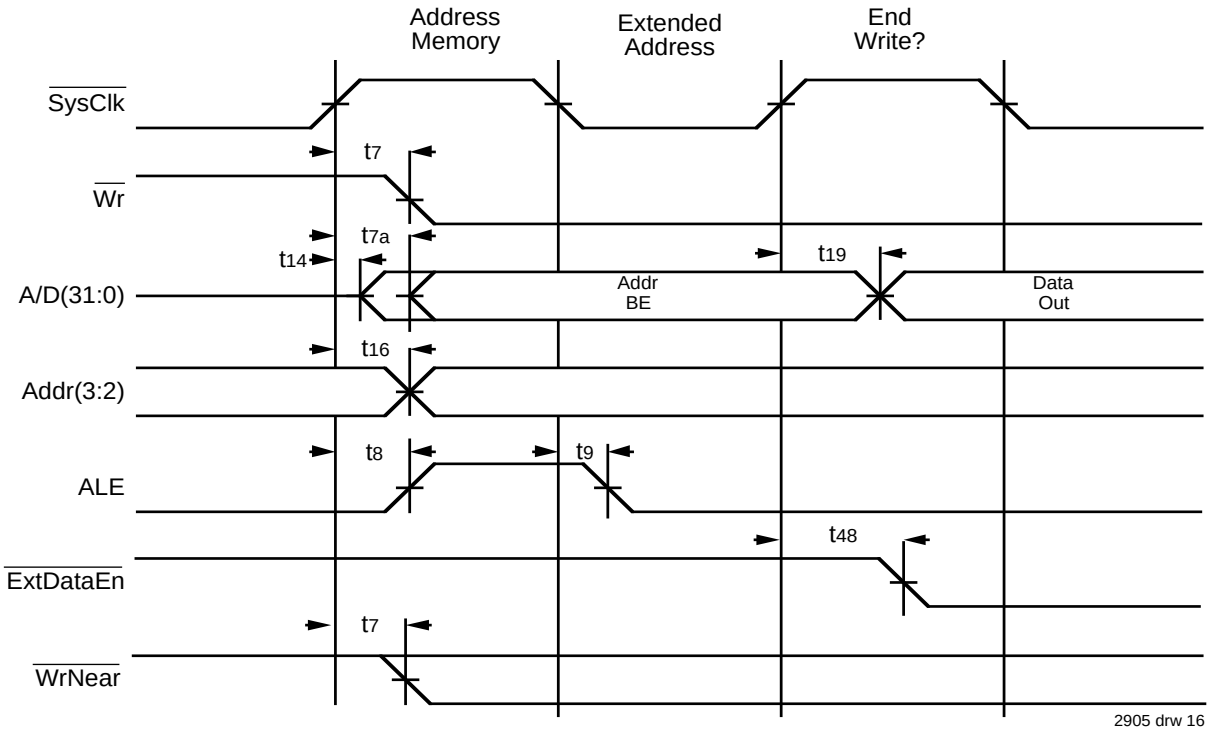


Figure 12(d). Start of Write Timing with Extended Address Hold Option

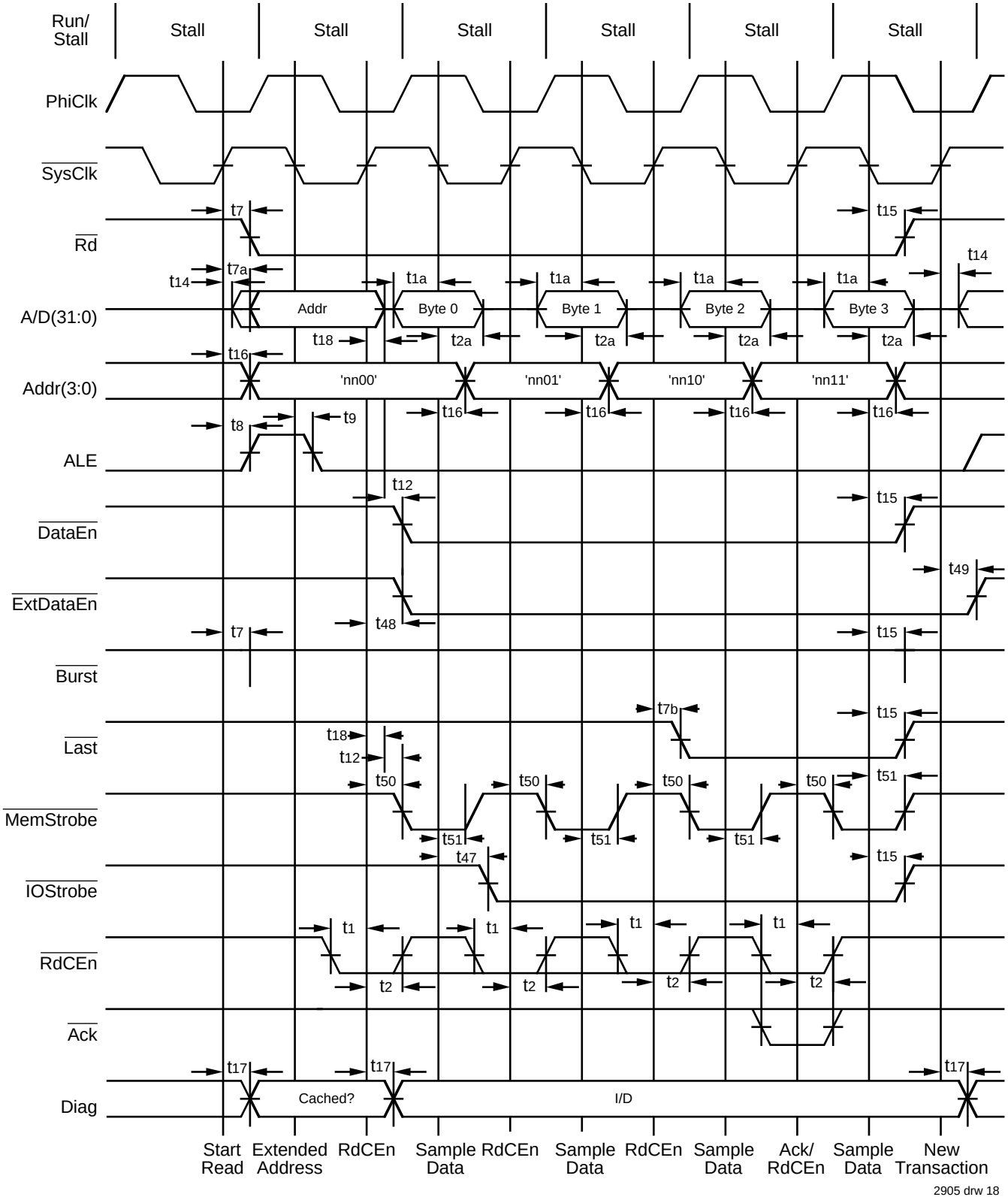


Figure 14. Mini-burst read of 32-bit datum from 8-bit wide memory port

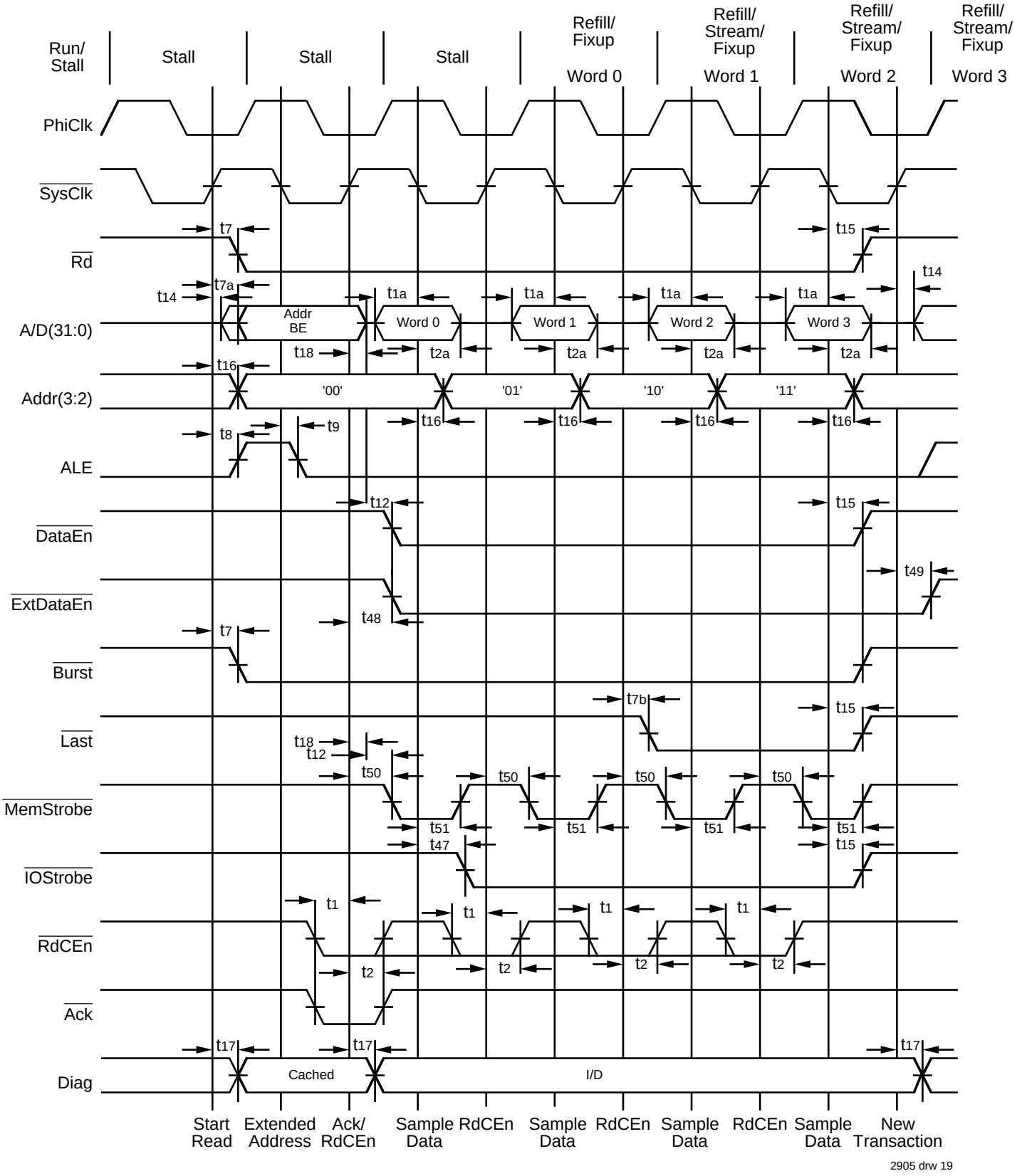


Figure 15. R3041 Quad Word Read

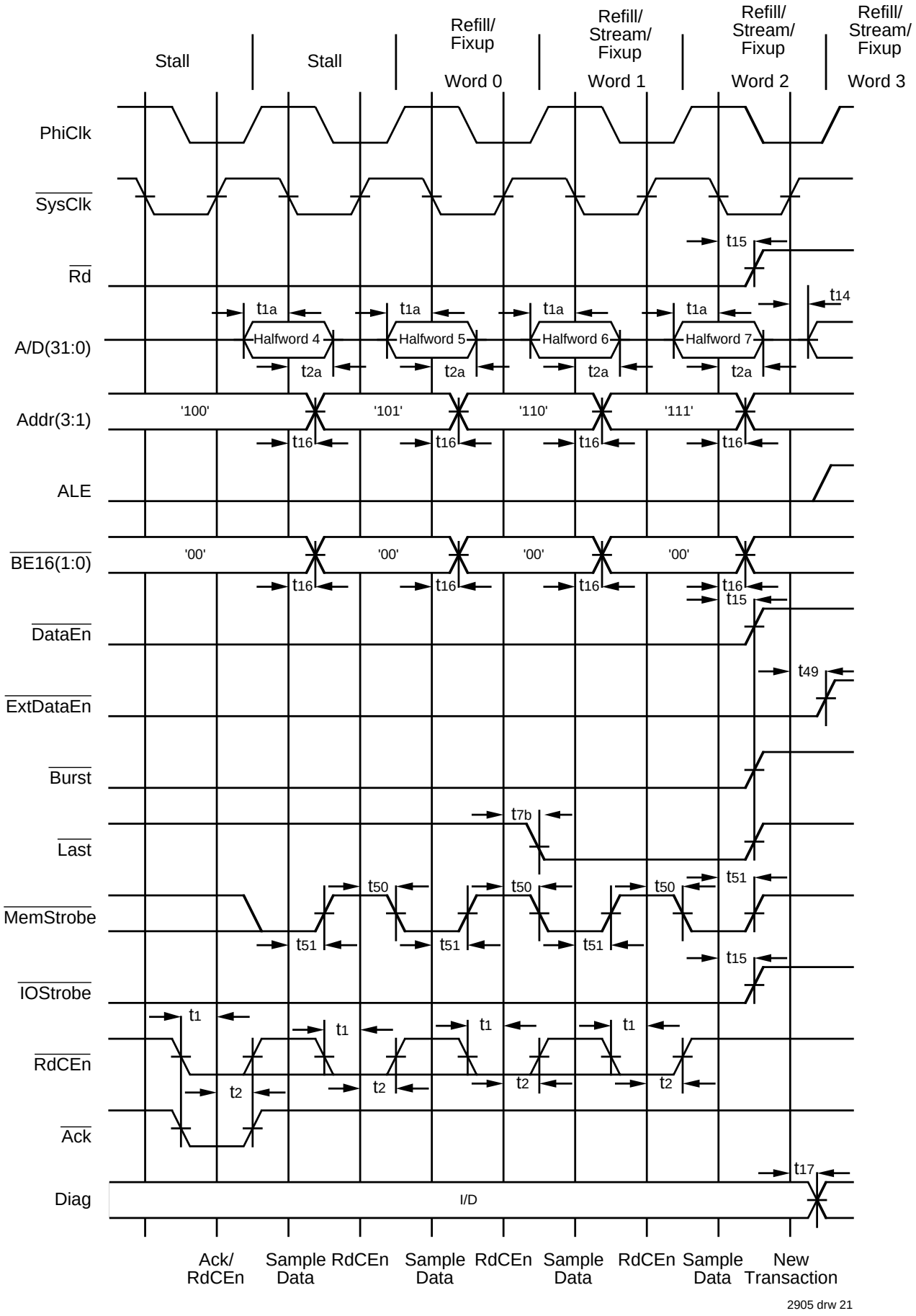


Figure 16(b). End of Quad Word read from 16-bit Wide Memory Port

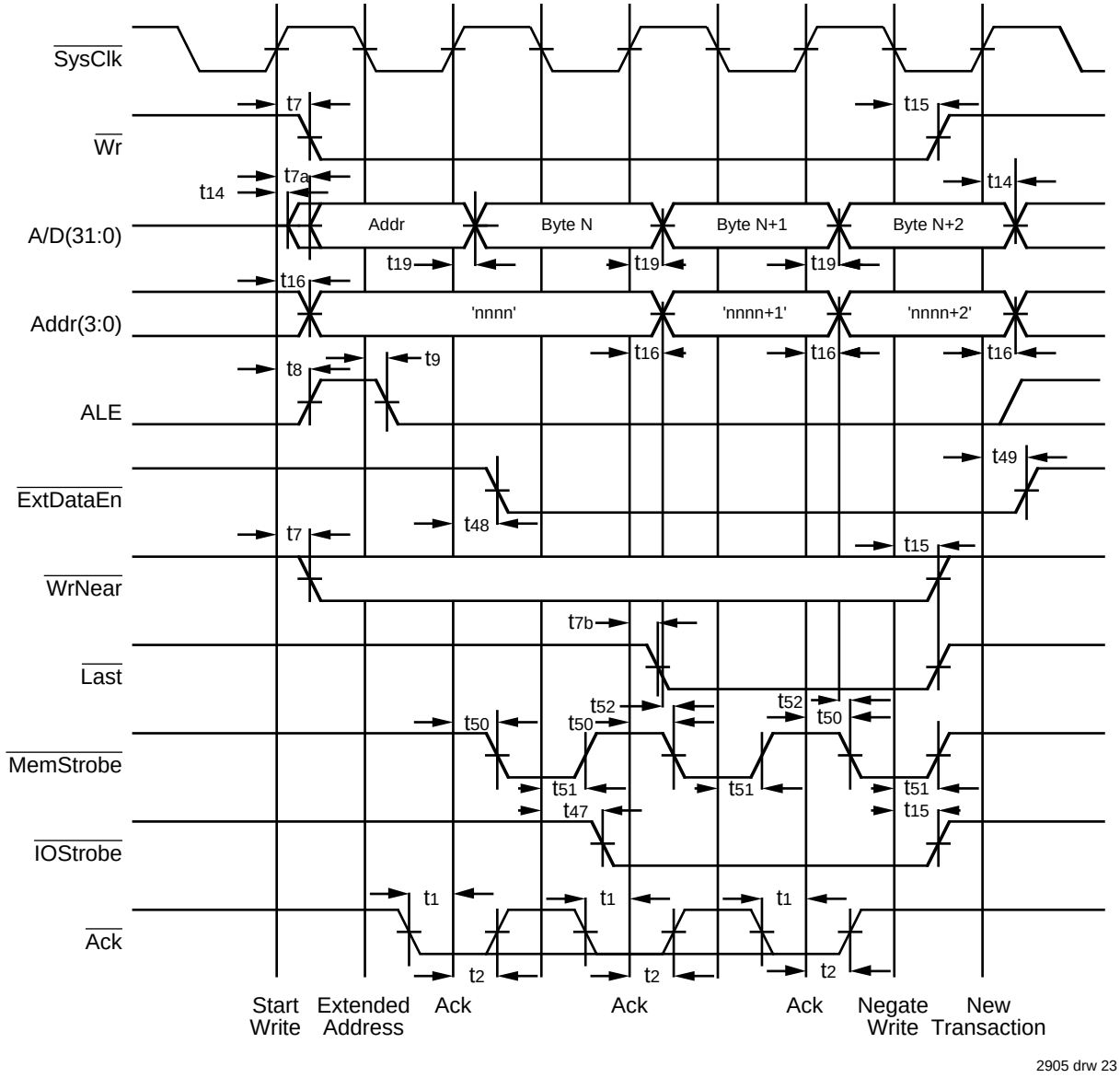


Figure 18. Tri-Byte Mini-burst Write to 8-bit Port

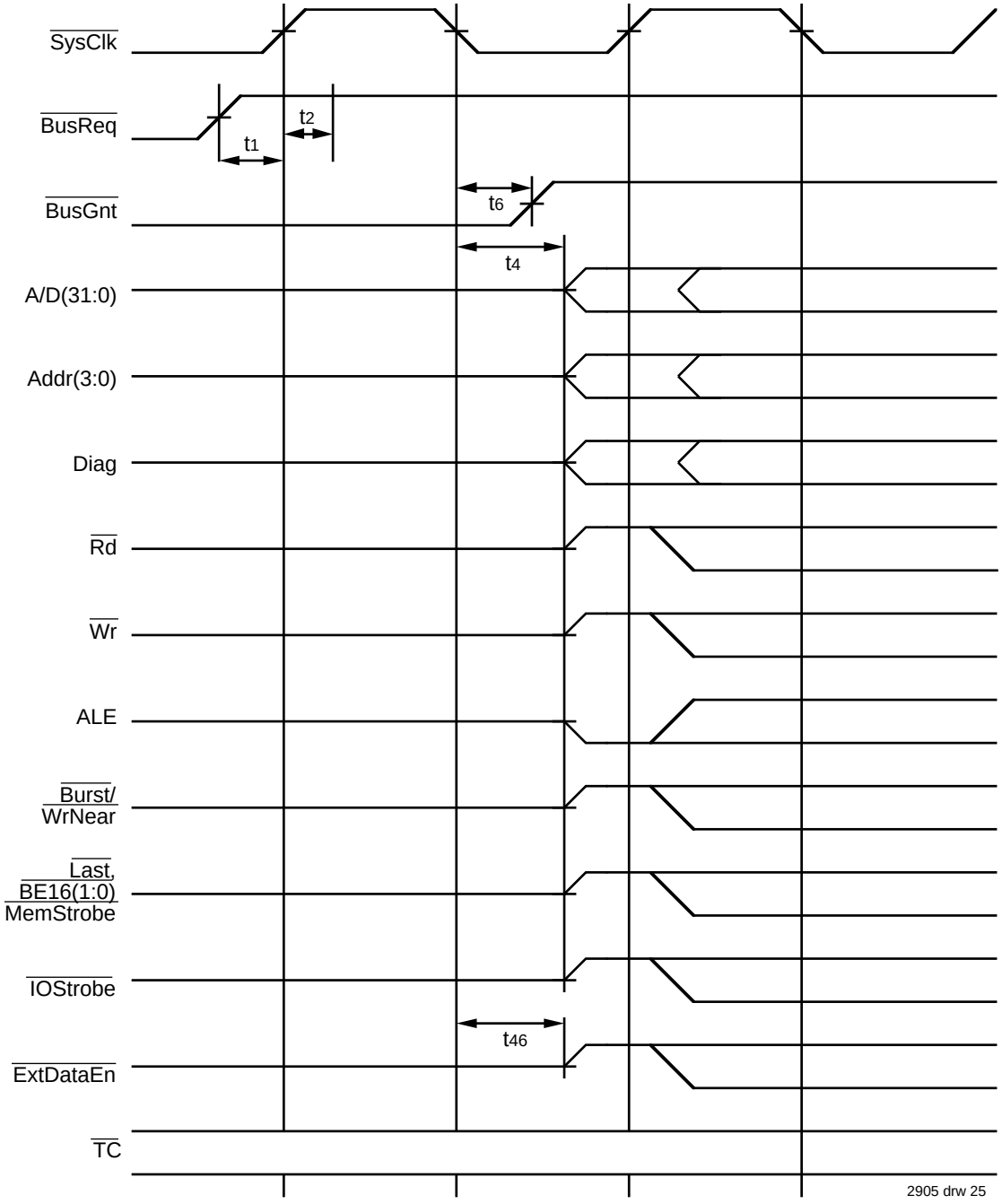


Figure 20. R3041 Regaining Bus Mastership

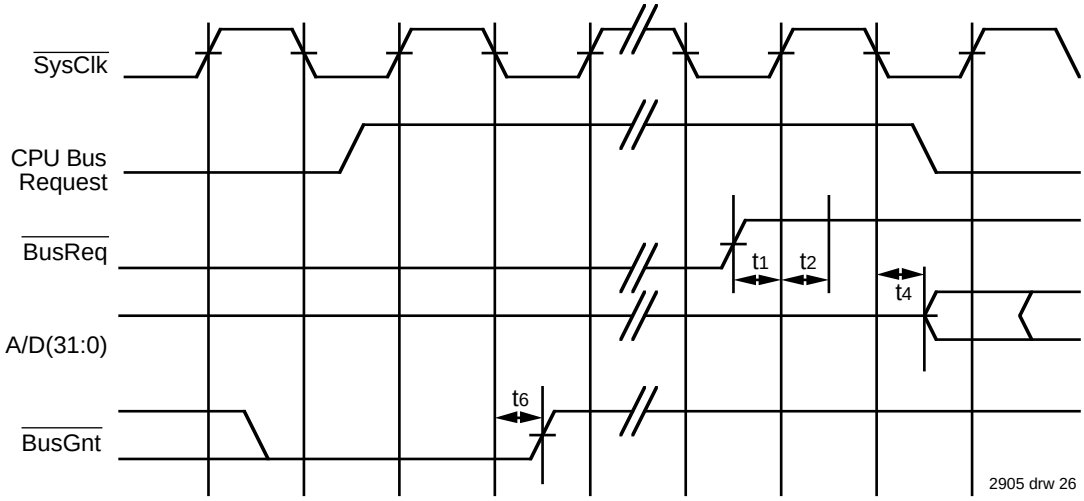


Figure 21. R3041 DMA Pulse Protocol

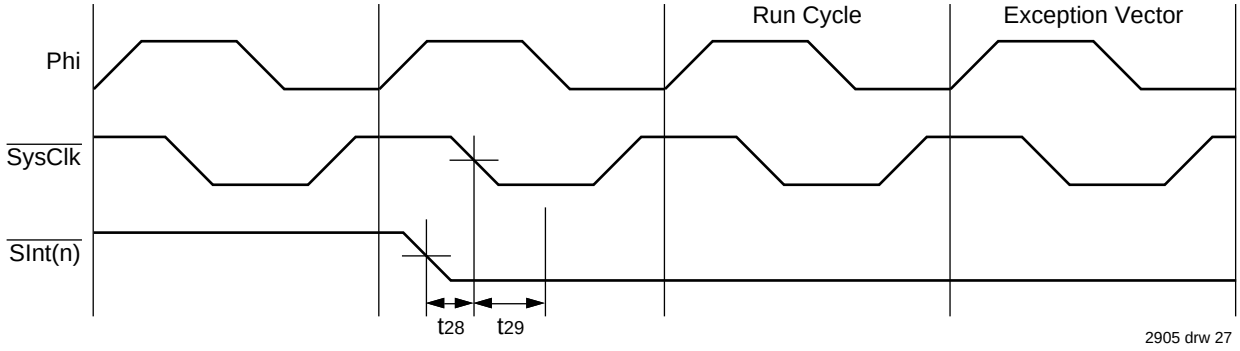


Figure 22. Synchronized Interrupt Input Timing

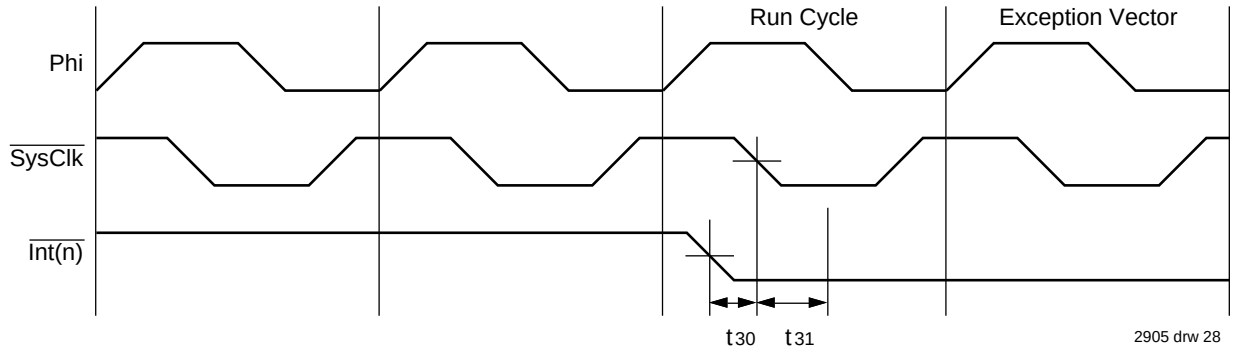


Figure 23. Direct Interrupt Input Timing

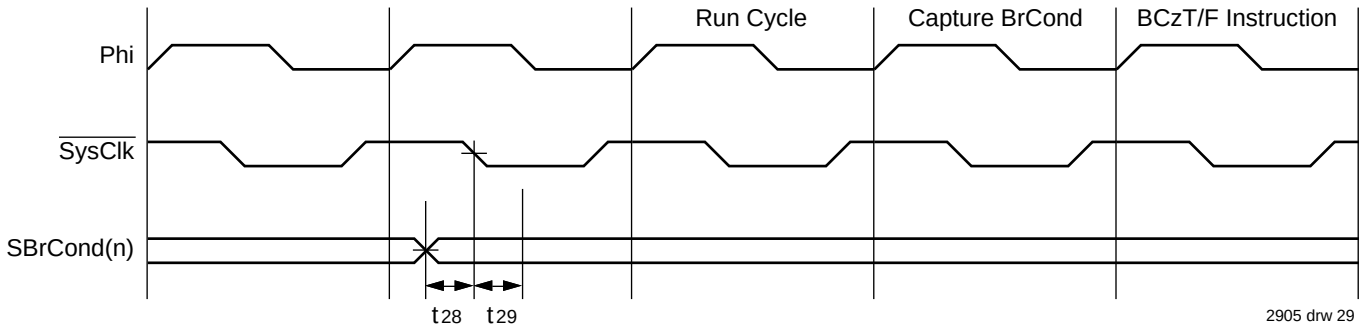


Figure 24. Synchronized Branch Condition Input Timing

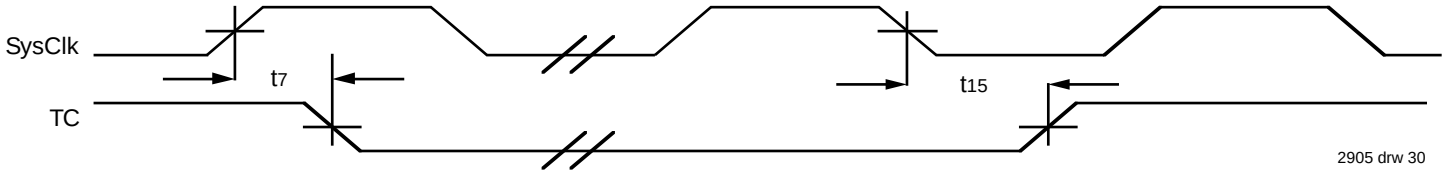
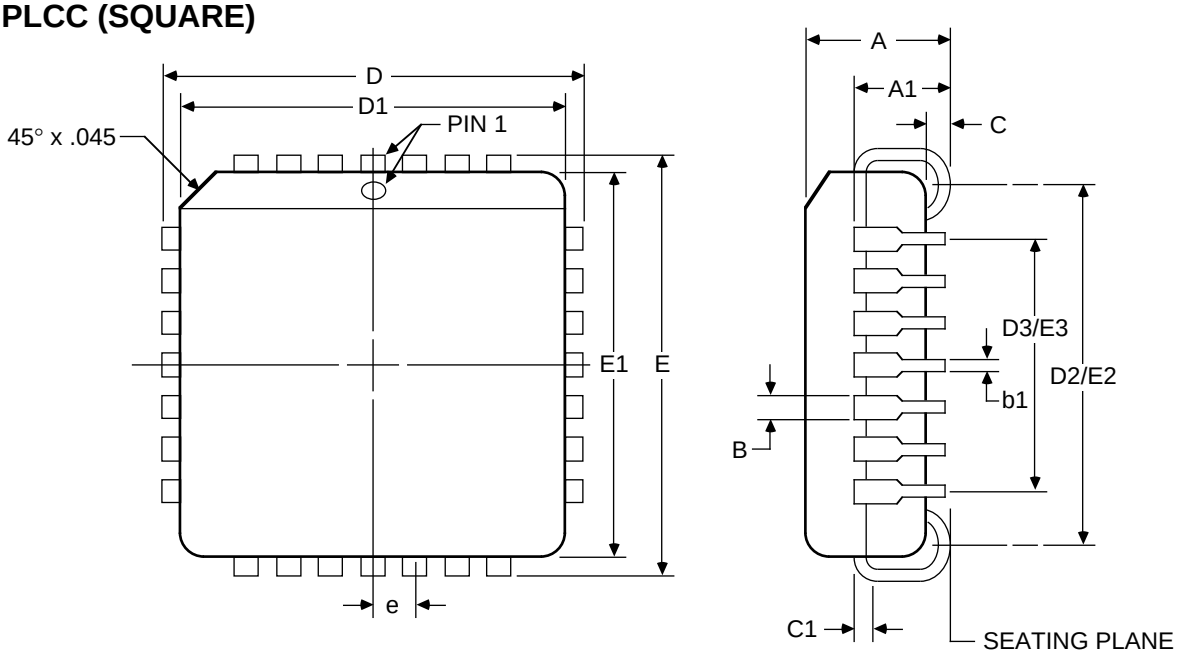


Figure 25. $\overline{TC}$ Output

84 LEAD PLCC (SQUARE)



DWG #	J84-1	
# of Leads	84	
Symbol	Min.	Max.
A	165	.180
A1	.095	.115
B	.026	.032
b1	.013	.021
C	.020	.040
C1	.008	.012
D	1.185	1.195
D1	1.150	1.156
D2/E2	1.090	1.130
D3/E3	1.000 REF	
E	1.185	1.195
E1	1.150	1.156
e	.050 BSC	
ND/NE	21	

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NOTES:
1. All dimensions are in inches, unless otherwise noted.
2. BSC—Basic lead Spacing between Centers.
3. D & E do not include mold flash or protutions.
4. Formed leads shall be planar with respect to one another and within .004" at the seating plane.
5. ND & NE represent the number of leads in the D & E directions respectively.
6. D1 & E1 should be measured from the bottom of the package.
7. PLCC is pin & form compatible with MQUAD; the MQUAD package is used in other RISController family members.